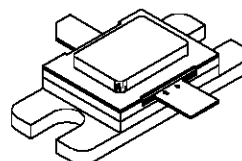


RF & MICROWAVE TRANSISTORS AVIONICS APPLICATIONS

- DESIGNED FOR HIGH POWER PULSED IFF AND DME APPLICATIONS
- 600 WATTS (typ.) IFF 1030/1090 MHz
- 550 WATTS (min.) DME 1025 - 1150 MHz
- 5.6 dB MIN. GAIN
- REFRACTORY GOLD METALLIZATION
- BALLASTING AND LOW THERMAL RESISTANCE FOR RELIABILITY AND RUGGEDNESS
- 30:1 LOAD VSWR CAPABILITY AT SPECIFIED OPERATING CONDITIONS
- INTERNAL INPUT/OUTPUT MATCHED, COMMON BASE CONFIGURATION

DESCRIPTION

The SD1542 is a hermetically sealed, gold metallized, silicon NPN power transistor. The SD1542 is designed for applications requiring high peak power and low duty cycles such as IFF and DME. The SD1542 is packaged in a hermetic metal/ceramic package with internal input/output matching, resulting in improved broadband performance and a low thermal resistance.



.400 x .500 2LFL (M112)
hermetically sealed

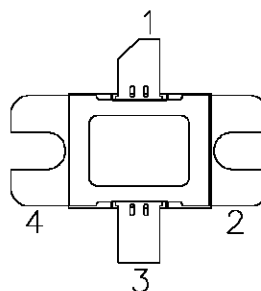
ORDER CODE

SD1542

BRANDING

SD1542

PIN CONNECTION



- | | |
|--------------|------------|
| 1. Collector | 3. Emitter |
| 2. Base | 4. Base |

ABSOLUTE MAXIMUM RATINGS ($T_{case} = 25^{\circ}C$)

Symbol	Parameter	Value	Unit
V_{CBO}	Collector-Base Voltage	65	V
V_{CES}	Collector-Emitter Voltage	65	V
V_{EBO}	Emitter-Base Voltage	3.5	V
I_C	Device Current	40	A
P_{DISS}	Power Dissipation	1350	W
T_J	Junction Temperature	+200	$^{\circ}C$
T_{STG}	Storage Temperature	- 65 to +200	$^{\circ}C$

THERMAL DATA

$R_{TH(j-c)}$	Junction-Case Thermal Resistance	0.06	$^{\circ}C/W$
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SD1542

ELECTRICAL SPECIFICATIONS ($T_{case} = 25^{\circ}C$)

STATIC

Symbol	Test Conditions	Value			Unit
		Min.	Typ.	Max.	
BV_{CBO}	$I_C = 25mA$ $I_E = 0mA$	65	—	—	V
BV_{CES}	$I_C = 50mA$ $V_{BE} = 0V$	65	—	—	V
BV_{EBO}	$I_E = 10mA$ $I_C = 0mA$	3.5	—	—	V
I_{CES}	$V_{CE} = 50V$ $I_E = 0mA$	—	—	35	mA
h_{FE}	$V_{CE} = 5V$ $I_C = .25A$	5	—	200	—

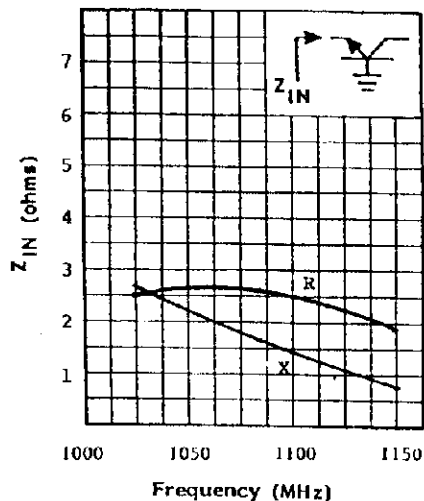
DYNAMIC

Symbol	Test Conditions	Value			Unit
		Min.	Typ.	Max.	
P_{OUT}	$f = 1025 \text{ — } 1150MHz$ $P_{IN} = 150 \text{ W}$ $V_{CE} = 50 \text{ V}$	550	—	—	W
G_p	$f = 1025 \text{ — } 1150MHz$ $P_{IN} = 150 \text{ W}$ $V_{CE} = 50 \text{ V}$	5.6	—	—	dB

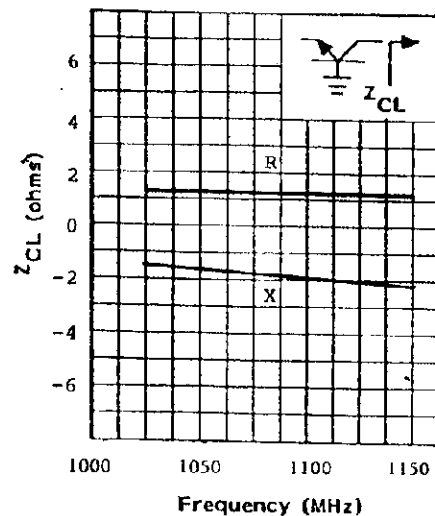
Note: Pulse Width = $10\mu Sec$, Duty Cycle = 1%

IMPEDANCE DATA

TYPICAL INPUT IMPEDANCE



TYPICAL COLLECTOR LOAD IMPEDANCE

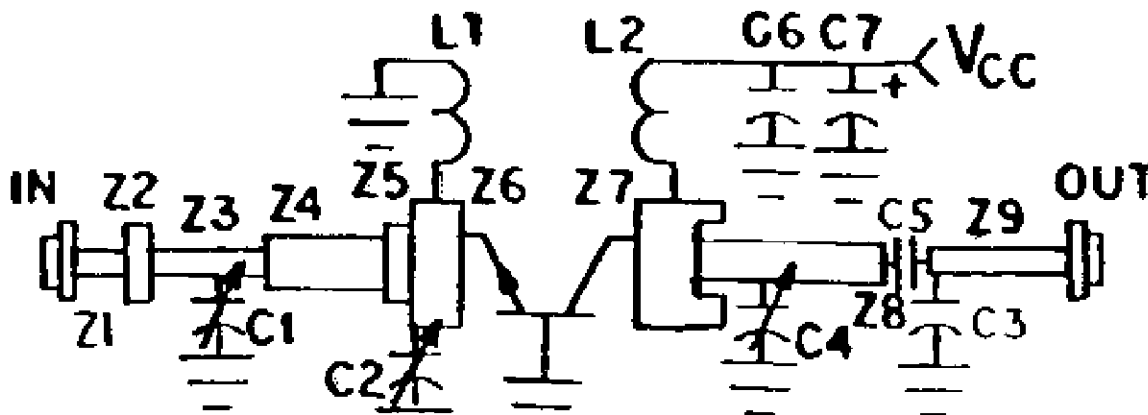


FREQ.	$Z_{IN} (\Omega)$	$Z_{CL} (\Omega)$
1020 MHz	$1.78 + j 3.0$	$1.33 - j 2.7$
1090 MHz	$1.57 + j 2.1$	$1.64 - j 3.4$
1150 MHz	$1.55 + j 1.4$	$1.93 - j 4.0$

$P_{IN} = 150 \text{ W}$

$V_{CE} = 50 \text{ V}$

TEST CIRCUIT



All Dimensions are in inches Unless Otherwise Specified

C1 : 0.4 - 2.5pF Johanson Gigatrim

C2, C3,

C4 : 0.6 - 4.5pF Johanson Gigatrim

C5 : 82pF Chip Capacitor, .055 Sq.

C6 : Pair of 820pF Chip Capacitors, .11 Sq.

C7 : 1000 μ F Electrolytic

L1 : Loop, #18 Tinned, .36 Wide x .27 Above Circuit

L2 : 4 3/4 Turns, #24 Enameled, Close Wound, .075 I.D.

Z1 : 50Ω (.02 Wide)

Z2 : .250 x .120

Z3 : 50Ω, .020 x .330; C1 Tapped .15 From Load

Z4 : .145 x .920

Z5 : .325 x .180

Z6 : .730 x .315

Z7 : .710 x .425 with .140 x .150 Cutout

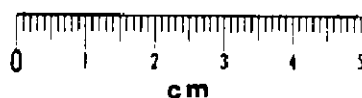
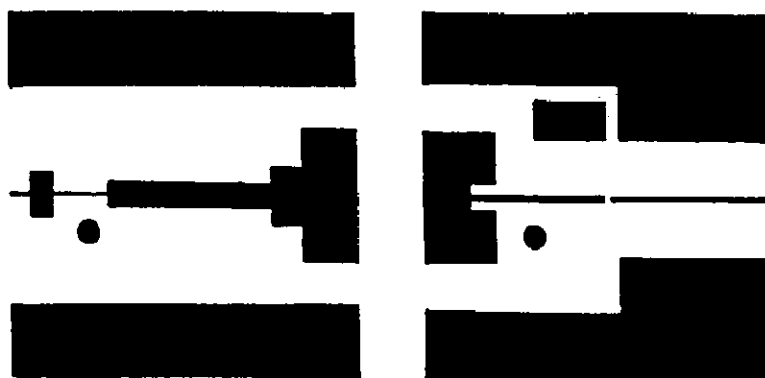
Z8 : .035 x .780; C4 Tapped .36 from Center

Z9 : 50Ω (.02 Wide)

C1, C4 : Cold End Terminated Through Eyelet

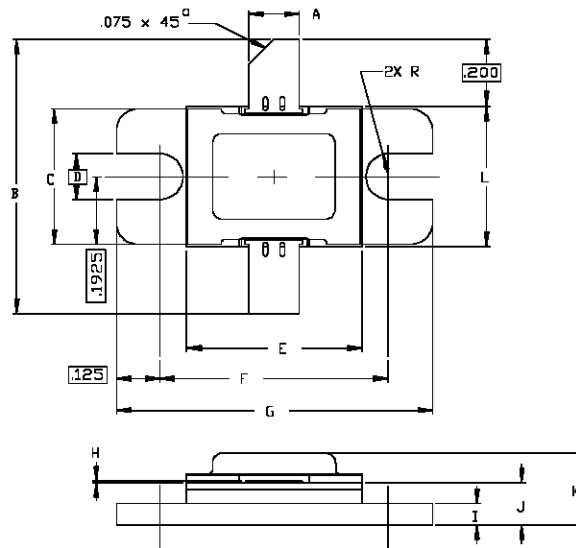
PC BOARD LAYOUT

3M EPSILAM 10, .032 THK., 10Z.



PACKAGE MECHANICAL DATA

Ref.: Dwg. No.12-0112



SGS-THOMSON MICROELECTRONICS		
	MINIMUM Inches/mm	MAXIMUM Inches/mm
A	.145/3,68	.155/3,93
B	.750/19,05	
C	.380/9,65	.390/9,91
D	.130/3,30	
E	.495/12,57	.507/12,88
F	.640/16,26	.655/16,64
G	.890/22,61	.910/23,11
H	.002/0,05	.006/0,15
I	.055/1,40	.065/1,65
J	.115/2,92	.135/3,43
K		.230/5,84
L	.395/10,03	.407/10,34

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